

A

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MTSUBOSHI BELTING LTD MU A 2000.08.29  
2000.08.29 2000-258425(+2000JP-258425) (2002.03.08) C03C 17/38,  
C23C 18/18, 18/31  
**Pattern plating method for glass substrate, involves fixing metal microparticle to silane connecting agent on glass substrate and removing resist film from masked substrate region**  
C2002-109732

NOVELTY

The glass substrate regions except a desired pattern region is masked by a resist film (2). The glass substrate surface (1) is treated by a silane connecting agent (7) which has a functional group chosen from a ureido group. A metal microparticle (3) is fixed to the silane connecting agent. A non-electrolytic plating is given to the glass substrate and the resist film is removed from the masked region.

DESCRIPTION OF DRAWING

The figure shows a glass substrate on which a metal particle is fixed through a silane connecting agent fixed to the substrate.

Glass substrate surface 1

Resist film 2

Metal microparticle 3

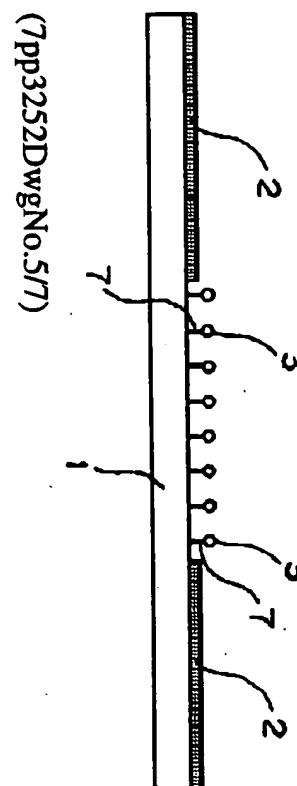
Silane connecting agent 7

DETAILED DESCRIPTION

An INDEPENDENT CLAIM is included for glass substrate.

USE

For pattern plating on glass substrate (claimed).



(7pp3252DwgNo.5/7)